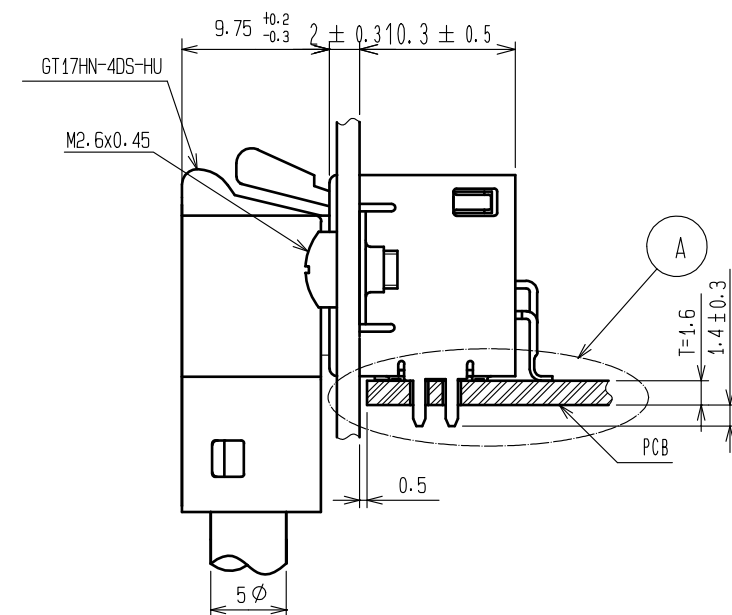
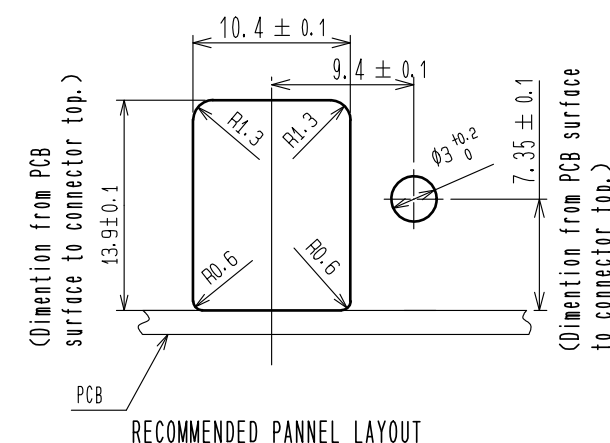
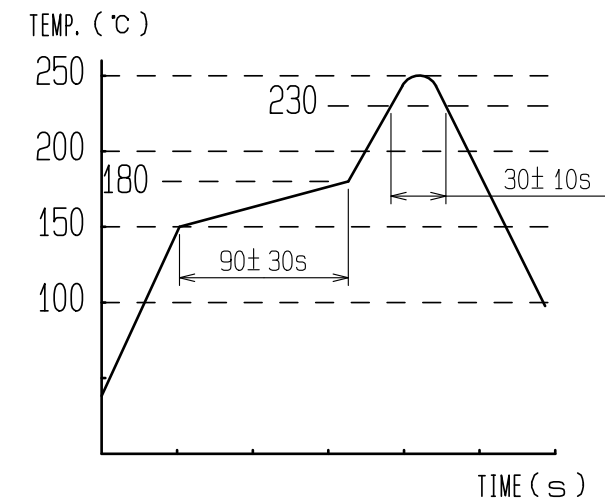
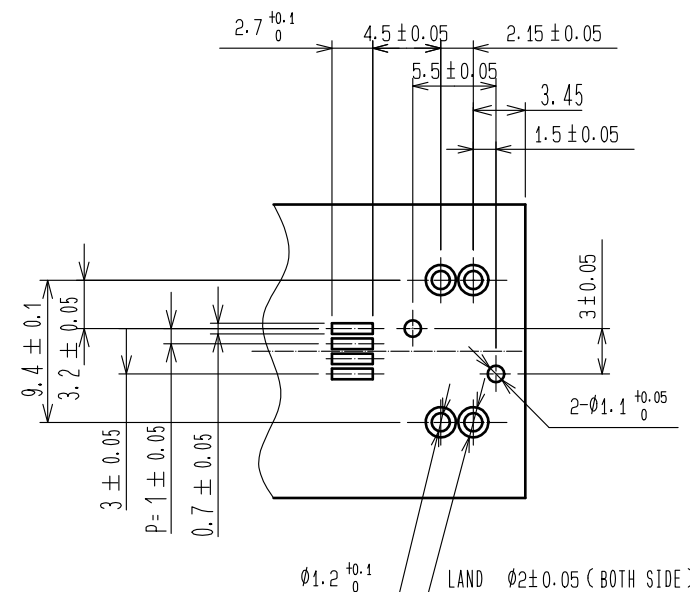
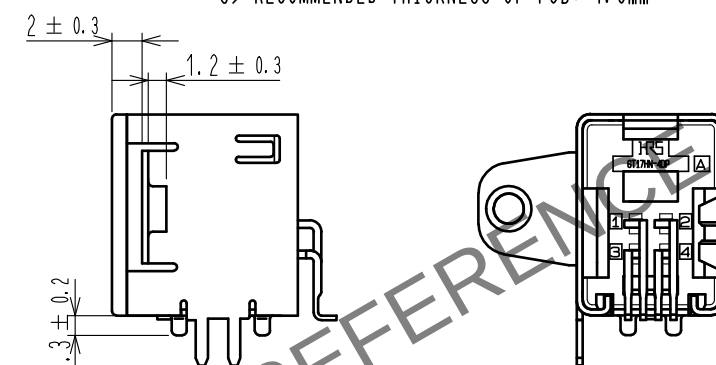
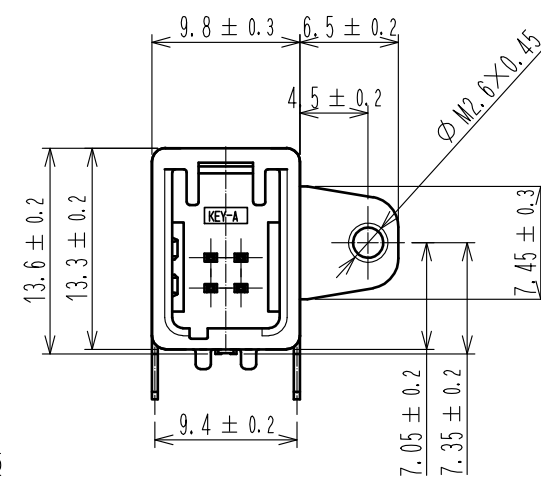
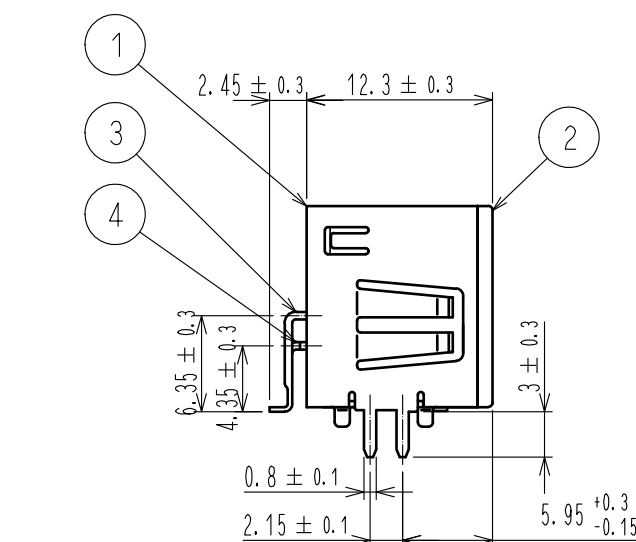


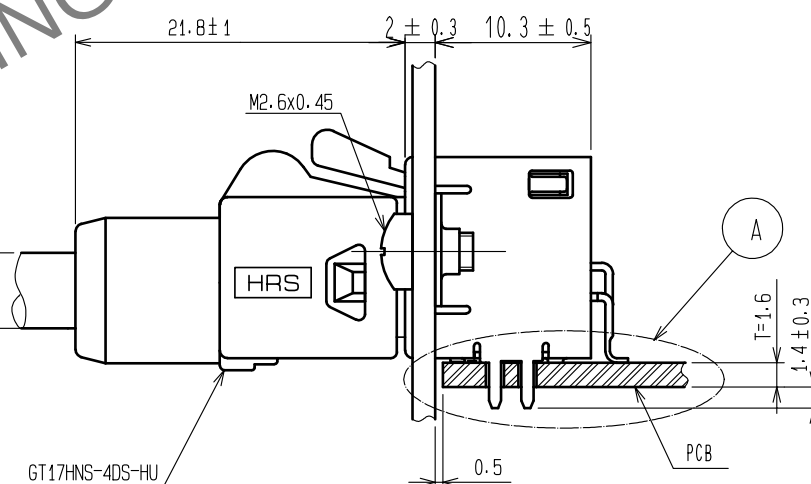
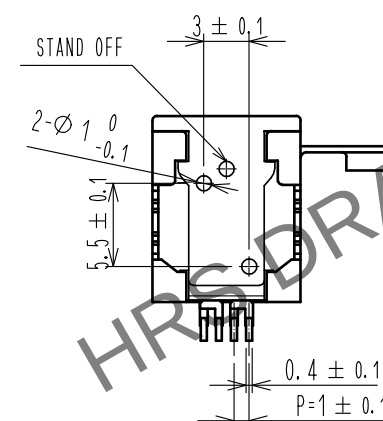
- 1) CONTACT COPLANARITY: 0.1mm MAX.
- 2) RECOMMENDED THICKNESS OF SOLDERING PASTE: 0.15mm
- 3) RECOMMENDED REFLOW PROFILE (SEE RIGHT GRAPH)
TYPE:IR REFLOW
ATMOSPHERE: FAR INFRARED RAY, AIR OR N2
CYCLE TIME: UP TO 2 CYCLES OF REFLOW SOLDERING ARE POSSIBLE
UNDER THE CONDITIONS, PROVIDED THAT THERE IS
A RETURN TO NORMAL TEMPERATURE BETWEEN THE FIRST
AND SECOND CYCLE.
PEAK TEMPERATURE: 250°C
230°C MIN. FOR 20 TO 40 SECONDS.
PREHEATING AREA 150°C FOR 60 TO 120 SECONDS.
- 4) HAND SOLDERING: 280-300°C, 2S MAX.
- 5) RECOMMENDED THICKNESS OF PCB: 1.6mm



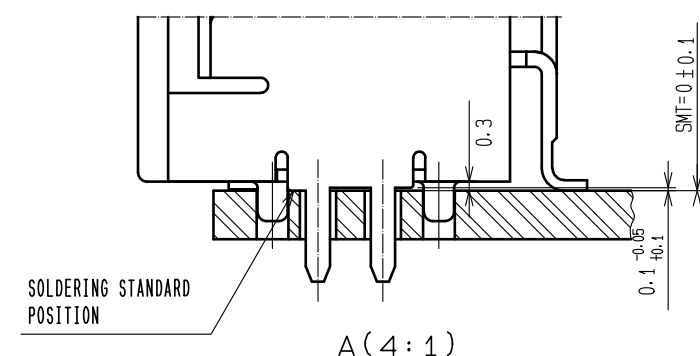
IN COMBINATION WITH RIGHT-ANGLE CONNECTOR

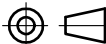


RECOMMENDED PCB LAYOUT



IN COMBINATION WITH STRAIGHT CONNECTOR

 $A(4:1)$

2	PPS	BROWN		4	BRASS	TIN PLATING			
1	COPPER ALLOY	TIN PLATING		3	BRASS	TIN PLATING			
NO.	MATERIAL	FINISH , REMARKS		NO.	MATERIAL	FINISH , REMARKS			
UNITS mm 	HIROSE ELECTRIC CO., LTD.	SCALE 2 : 1		COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE	
		APPROVED +KI. HIROKAWA		20200331	DRAWING NO. EDC-167690-55-00				
		CHECKED +EJ. WAKATSUKI		20200330	PART NO. GT17HNR-4DP-2H(A)(55)				
		DESIGNED +TS. KUBOTA		20200325	CODE NO. CL767-0230-6-55				
DRAWN +YK. MITSUISHI		20200317	1/						